

SHARP

OPTO-ELECTRONIC DEVICES DIVISION ELECTRONIC COMPONENTS GROUP SHARP CORPORATION

SPECIFICATION

DEVICE SPECIF	TCATION FOR	
	PHOTOTRANSISTO	R
MODEL No.	PT480FE0000F	
Specified for		
	ntents, please be sure to send b	nsists of 9 pages including cover. ack copy of the Specifications
CUSTOMER'S APPROVAI		PRESENTED
DATE .		DATE
ВҮ	·	BY /\d 0
		H. Ogura, Department General Manager of Engineering Dept.,III Opto-Electronic Devices Div. ELECOM Group SHARP CORPORATION

REFERENCE

Product name: PHOTOTRANSISTOR

Model No.: PT480FE0000F

1.	These specification sheets include materials protected under copyright of Sharp Corporation ("Sharp").	•
	Please do not reproduce or cause anyone to reproduce them without Sharp's consent.	

2. When using this product, please observe the absolute maximum ratings and the instructions for use outlined in these specification sheets, as well as the precautions mentioned below. Sharp assumes no responsibility for any damage resulting from use of the product which does not comply with the absolute maximum ratings and the instructions included in these specification sheets, and the precautions mentioned below.

(Precautions)

(1) This product is designed for use in the following application areas;

OA equipment · Audio visual equipment · Home appliances
· Telecommunication equipment (Terminal) · Measuring equipment
· Tooling machines · Computers

If the use of the product in the above application areas is for equipment listed in paragraphs

If the use of the product in the above application areas is for equipment listed in paragraphs (2) or (3), please be sure to observe the precautions given in those respective paragraphs.

- (2) Appropriate measures, such as fail-safe design and redundant design considering the safety design of the overall system and equipment, should be taken to ensure reliability and safety when this product is used for equipment which demands high reliability and safety in function and precision, such as;
 - Transportation control and safety equipment (aircraft, train, automobile etc.)
 - · Traffic signals · Gas leakage sensor breakers · Rescue and security equipment
 - Other safety equipment
- (3) Please do not use this product for equipment which require extremely high reliability and safety in function and precision, such as;
 - Space equipment Telecommunication equipment (for trunk lines)
 - · Nuclear power control equipment · Medical equipment
- (4) Please contact and consult with a Sharp sales representative if there are any questions regarding interpretation of the above three paragraphs.
- 3. Please contact and consult with a Sharp sales representative for any questions about this product.



1. Application

This specification applies to the outline and characteristics of Silicon phototransistor Model No. PT480FE0000F.

2. Outline

Refer to the attached drawing No. CY12976H02, page 3.

3. Ratings and characteristics

Refer to the attached sheet, page 4, 5.

4. Reliability

Refer to the attached sheet, page 6.

5. Outgoing inspection

Refer to the attached sheet, page 7.

6. Supplement

(6-1) Packing

Refer to the attached sheet, page 8.

- (6-2) This product is not designed against electromagnetic and ionized-particle irradiation.
- (6-3) This product shall not contain the following materials.

Also, the following materials shall not be used in the production process for this product.

Materials for ODS: CFCs, Halon, Carbon tetrachloride

1,1,1-Trichloroethane (Methyl chloroform)

- (6-4) This product does not contain the chemical materials regulated by RoHS.
- (6-5) This product does not contain specific brominated flame retardants such as the PBBOs and PBBs.
- (6-6) Product mass (Piece): Approximately 0.09g

7. Notes

(7-1) Cleaning conditions:

Solvent cleaning:

Solvent temperature 45°C or less Immersion for 3 min or less

Ultrasonic cleaning:

The effect to device by ultrasonic cleaning differs by cleaning bath size, ultrasonic power

output, cleaning time, PCB size or device mounting condition etc.

Please test it in actual using condition and confirm that doesn't occur any defect before starting

the ultrasonic cleaning.

The cleaning shall be carried out with solvent below.

Solvent: Ethyl alcohol, Methyl alcohol, Isopropyl alcohol

(7-2) Soldering

The lead pins should be soldered according to the absolute maximum ratings.

While or after soldering, the lead pins shall be free from external force.

This device shall not be soldered with preheat or reflow.

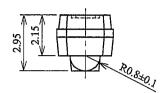
The terminal covering of this device consists of lead free solder.

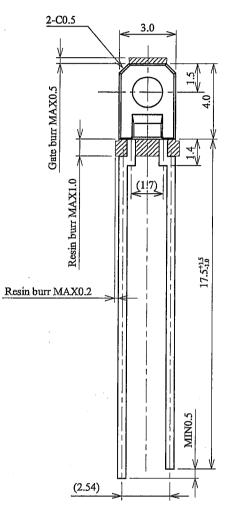
In case of mounting this device in a lead free soldering process, special care should be taken to avoid

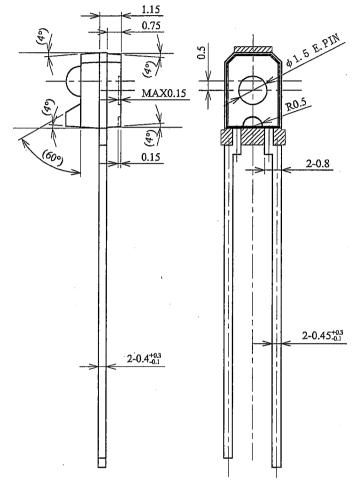
any boundary exfoliation (Lift-off phenomenon) between the solder and the solder pad on the printed circuit board.

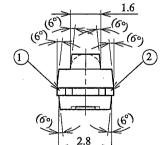
REFERENCE PT480F1000











- 1) Unspecified tolerance shall be ± 0.2 .
- 2) Package: Black (Visible light cut-off resin)
- 3) Dimensions in parenthesis are shown for reference.
- 4) The thin burn thickness (MAX. 0.05mm) and the gate burn (MAX. 0.5mm) shall not be inclusive to the outline dimensions.
- 5) Protruded resin 1.0mm MAX. However, the thin burr with a lead attached is 1.4mm MAX. from the resin.

Pin name

Terminal connection

1 Emitter

(2) Collector



Scale	Material	Finish	**	PT480FE0000F
1	Lead : Fe	Lead pin: Solder dip	Name	Outline Dimensions
$\frac{\text{Unit}}{1 = \frac{1}{1} \text{ mm}}$	Package: Epoxy resin	Lead-free solder use Composition(Standard value) Sn96.5%,Ag3.0%,Cu0.5%	Drawing No.	C Y 1 2 9 7 6 H 0 2



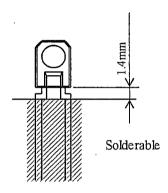
3. Ratings and characteristics

3.1 Absolute maximum ratings

Ta=25℃

Parameter	Symbol	Rating	Unit
Collector-emitter voltage	V _{CEO}	35	V
Emitter-collector voltage	V _{ECO}	6	V
Collector current	I_{C}	20	mA
Collector power dissipation	P _C	75	mW
Operating temperature	T _{Opr}	-25 to +85	$^{\circ}$
Storage temperature	T_{Stg}	-40 to +85	$^{\circ}\mathbb{C}$
* Soldering temperature	T _{Sol}	260	$^{\circ}$

* For 5 seconds MAX, at the position of 1.4mm from the resin edge.



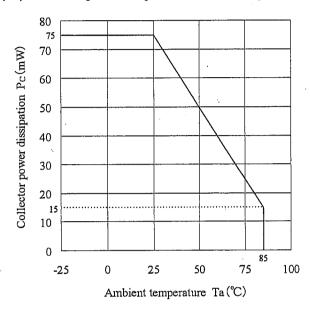
3.2 Electro-optical characteristics

Ta=25°C

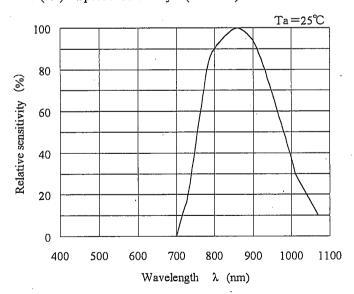
Parameter	Symbol	MIN.	TYP.	MAX.	Unit	Conditions
Collector current	I _C	0.25	0.8	3.0	mA	*Ee=1mW/cm² V _{CE} =5V
Dark current	I _{CEO}	ting the state of	1.0	100	nA	Ee=0, V _{CE} =20V
Collector-emitter saturation voltage	V _{CE(sat)}	-	0.1	0.4	V	*Ee=10mW/cm ² I _C =0.5mA
Collector-emitter breakdown voltage	BV _{CEO}	35	-	-	V	I _C =0.1mA Ee=0
Emitter-collector breakdown voltage	BV _{ECO}	6	-	-	V	I _E =0.01mA Ee=0
Peak sensitivity wavelength	λ_{P}	-	860	-	nm	_
Response time (Rise)	t _r	-	3.0	-	μs	V _{CE} =2V, Ic=2mA
Response time (Fall)	t _f	-	3.5	-	μs	$R_L=100\Omega$

※ Ee: Irradiance by CIE standard light source A (tungsten lamp)

(3.3) Collector power dissipation vs. ambient temperature



(3.4) Spectral sensitivity (reference)



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4. Reliability

The reliability of products shall satisfy items listed below.

Confidence level: 90%

LTPD: 10 or 20

		L1PD: 10 or 20			
Test Items	Test Conditions	Failure Judgement Criteria	Samples (n) Defective(C)		
Temperature cycling	1 cycle -40°C←→+85°C (30min) (30min) 20 cycles test		n=22, C=0		
High temp. and high humidity storage	+60°C,90%RH,500h		n=22, C=0		
High temp. storage	+85°C, 500h		n=22, C=0		
Low temp. storage	-40°C, 500h	,	n=22, C=0		
Operation life	Pc=75mW, Ta=25°C, 500h	$I_{C} < L \times 0.8$	n=22, C=0		
Mechanical shock	1000 m/s ² , 6ms, Half sine wave 3 times/ \pm X, \pm Y, \pm Z direction	$I_{C}>U\times1.2$ $I_{CEO}>U\times2.0$	n=11, C=0		
Variable frequency vibration	100 to 2000 to 100Hz/Sweep for 4min 200m/s ² , 48min/X, Y, Z direction	V _{CE(sat)} >U×1.2 U: Upper specification limit	n=11, C=0		
Terminal strength (Tension)	Weight: 5N 10 s/each terminal	L: Lower specification limit	n=11, C=0		
Terminal strength (Bending)	Weight: 2.5N $0^{\circ} \rightarrow 90^{\circ} \rightarrow 0^{\circ} \rightarrow -90^{\circ} \rightarrow 0^{\circ}$ The one test should be performed.		n=11, C=0		
Soldering heat	260±5°C, 5±0.5s Position of 1.4mm from the resin edge.		n=11, C=0		
Solderability	245±5°C, 5±1 s Position of 1.4mm from the resin edge. Flux:EC-19S (Tamura kaken corporation) No pretreatment	Solder shall adhere at less than 95% area of dipped portion.	n=11, C=0		



5. Outgoing inspection

(1) Inspection lot
Inspection shall be carried out per each delivery lot.

(2) Inspection method

A single sampling plan, normal inspection level II based on ISO2859 shall be adopted.

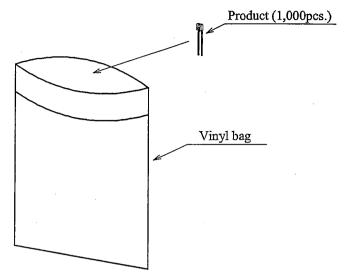
Defec	t	Inspection items and test method				AQL(%)				
	1	Disconnection, short								
	2	Inverse polarity on terminal								
	3	Characteristics defect								
		Parameter	Symbol	Judgemei	nt criteria	Unit				
		Parameter	Symbol	MIN.	MAX.	Cint				
Major		Collector current	I_{C}	0.25	3.0	mA	0.065			
defect		Dark current	I_{CEO}	•	100	nA	0.005			
		Collector-emitter	BV _{CEO}	35	-	V				
		breakdown voltage	D A CEO	<i>33</i> , I		V				
		Emitter-collector	BV_{ECO}	6.0	_	v				
		breakdown voltage	DVECO	0.0	0.0	,				
		Test conditions refer	to paragraph 3.2.							
	1	Appearance defect								
	Parameter			Judgement criteria						
		C 1	Visible crac	Visible crack irrespective of its						
Minor	Crack		position sha	position shall be defect.						
defect					Split, Chip,	01:-1	-0°441	atamiati aa		
		Scratch,	· ·	affects the cl		i ,				
		Stain, Blur	or paragrap	of paragraph 3.2. shall be defect.						

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6-1 Packaging

6-1-1 Inner packing

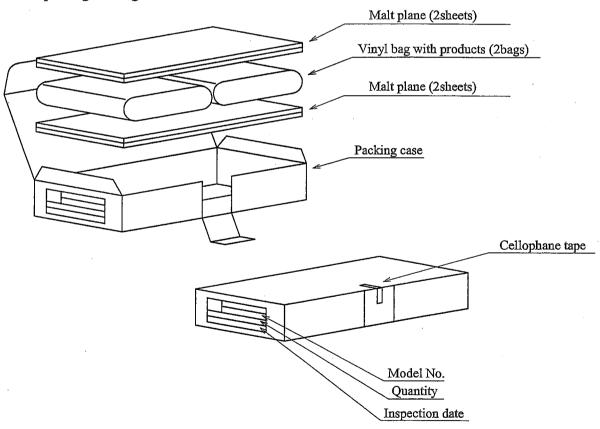
① Inner packing drawing



- ② Inner packing material: Vinyl bag (Polyethylene)
- 3 Quantity: 1,000pcs./bag

6-1-2 Outer packing

① Outer packing drawing



- ② Outer material: Packing case (Corrugated cardboard),
 Malt plane (Urethane), Cellophane tape
- 3 Quantity: 2,000pcs./box
- 4 Indication: Model No., quantity and inspection date
- ⑤ Regular packaged mass: Approximately 270g